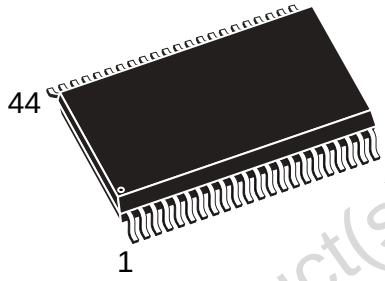
M68AW256D

4 Mbit (256K x16) 3.0V Asynchronous SRAM

FEATURES SUMMARY

- SUPPLY VOLTAGE: 2.7 to 3.6V
- 256K x 16 bits SRAM with OUTPUT ENABLE
- EQUAL CYCLE and ACCESS TIME: 55ns, 70ns
- SINGLE BYTE READ/WRITE
- LOW STANDBY CURRENT
- LOW V_{CC} DATA RETENTION: 1.5V
- TRI-STATE COMMON I/O
- AUTOMATIC POWER DOWN
- DUAL CHIP ENABLE for EASY DENSITY EXPANSION

Figure 1. Packages



TSOP44 Type II (ND)

TFBGA48 (ZB)
6 x 7 mm

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SUMMARY DESCRIPTION

The M68AW256D is a 4 Mbit (4,194,304 bit) CMOS SRAM, organized as 262,144 words by 16 bits. The device features fully static operation requiring no external clocks or timing strobes, with equal address access and cycle times. It requires a single 2.7 to 3.6V supply. This device has an automatic power-down feature, reducing the power consumption by over 99% when deselected.

The M68AW256D is available in TFBGA48 (0.75 mm pitch) and in TSOP44 Type II packages.

Figure 2. Logic Diagram

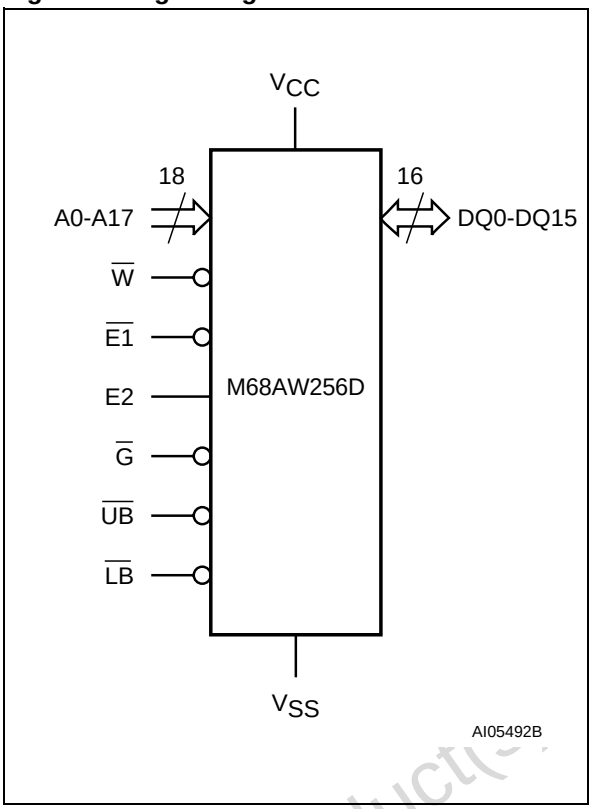


Table 1. Signal Names

A0-A17	Address Inputs
DQ0-DQ15	Data Input/Output
$\overline{E1}$, E2	Chip Enables
$\overline{G}$	Output Enable
$\overline{W}$	Write Enable
$\overline{UB}$	Upper Byte Enable Input
$\overline{LB}$	Lower Byte Enable Input
V_{CC}	Supply Voltage
V_{SS}	Ground
NC	Not Connected Internally
DU	Don't Use as Internally Connected

Figure 3. TSOP Connections

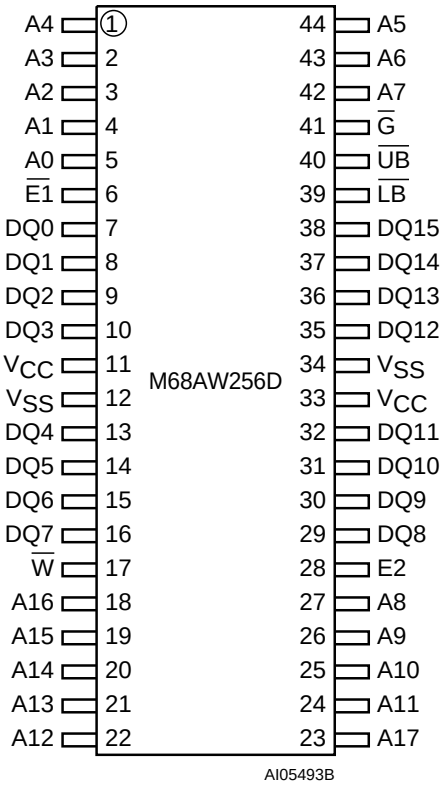


Figure 4. TFBGA Connections (Top view through package)

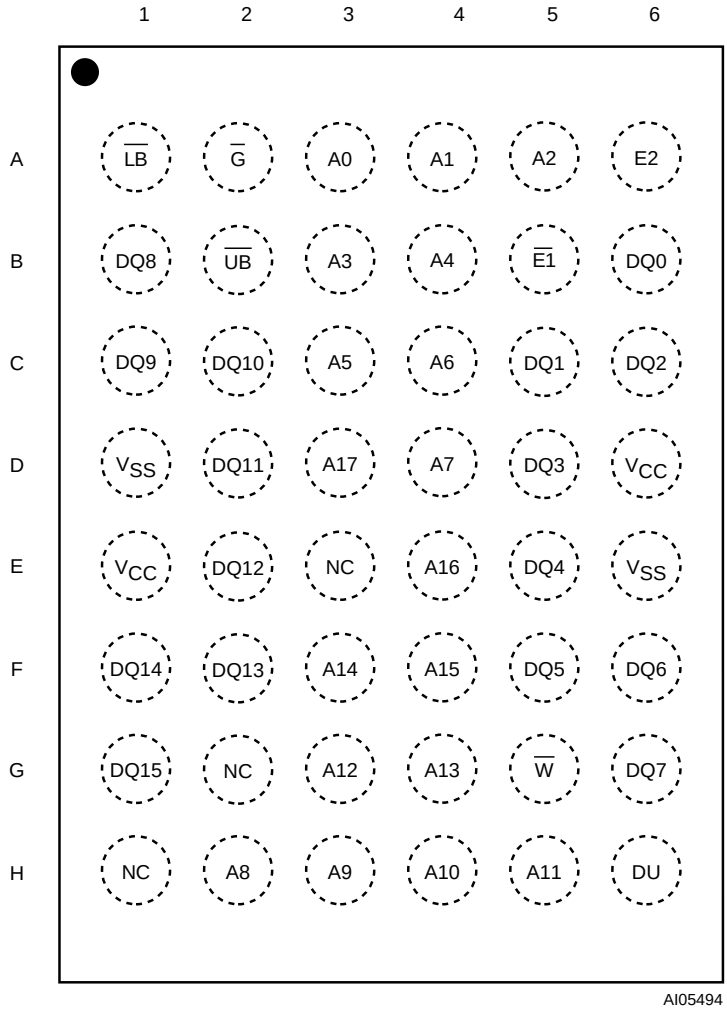
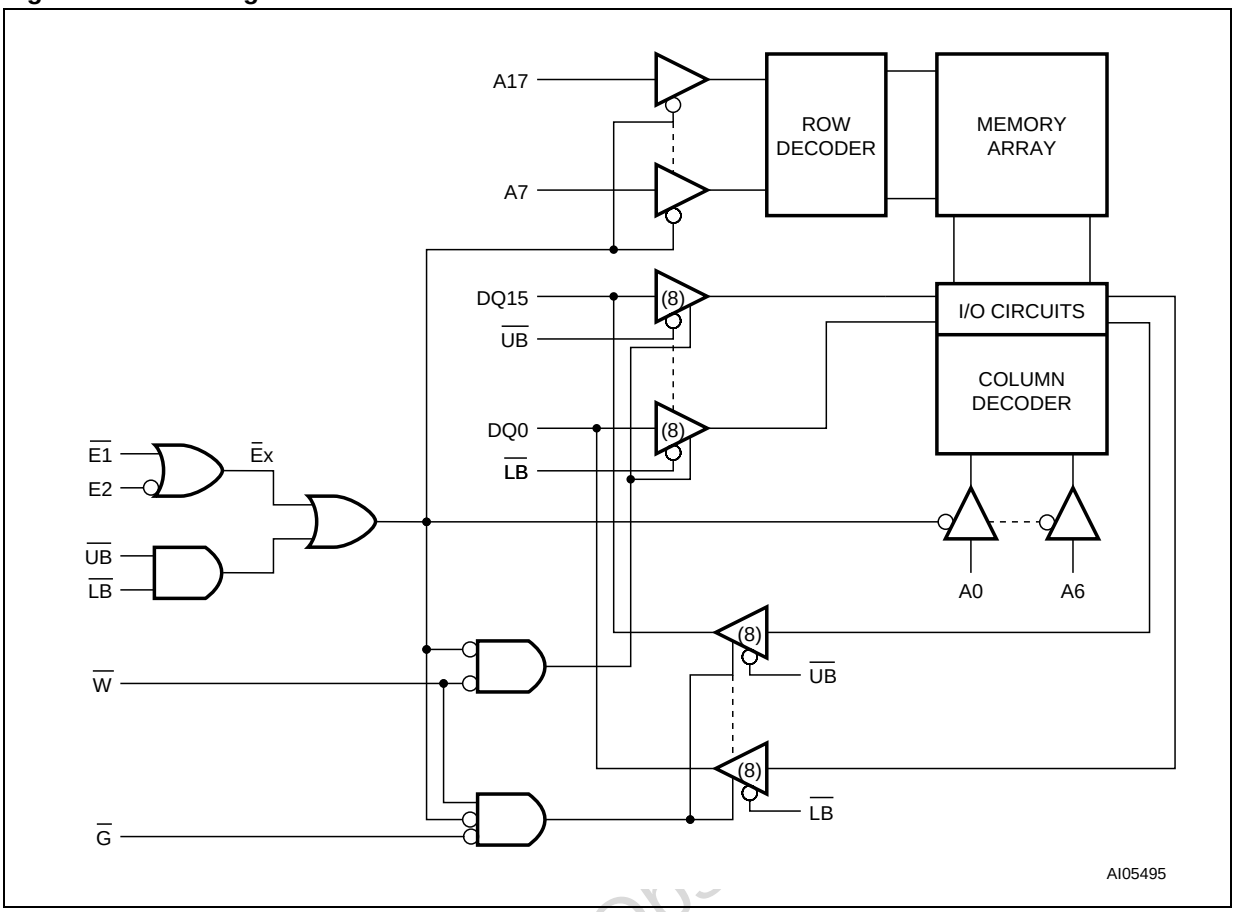


Figure 5. Block Diagram



OPERATION

The device has four standard operating modes:

Output Disabled, Read, Write and Standby/Power-Down. These modes are determined by the control inputs $\overline{E1}$, E2, $\overline{W}$, $\overline{G}$, $\overline{LB}$ and $\overline{UB}$ as summarized in Table 2.Operating Modes.

Output Disabled

The Output Enable signal, $\overline{G}$, provides high-speed tri-state control of DQ0-DQ15, allowing fast read/write cycles on the I/O data bus. The device is in Output Disabled mode when Output Enable, $\overline{G}$, is High. In this mode, $\overline{LB}$ and $\overline{UB}$ are Don't care and DQ0-DQ15 are high impedance.

Read Mode

The M68AW256D is in Read mode whenever the device is selected (Chip Enable $\overline{E1}$ at V_{IL} and Chip Enable E2 at V_{IH}), Write Enable, $\overline{W}$, is at V_{IH}, Output Enable, $\overline{G}$, is at V_{IL} and at least one of the Byte Enable inputs, $\overline{UB}$ and $\overline{LB}$, is at V_{IL}.

If only one of the Byte Enable inputs is at V_{IL}, the M68AW256D is in Byte Read mode. If the two Byte Enable inputs are at V_{IL}, the M68AW256D is in Word Read mode. So depending on the status of the $\overline{UB}$ and $\overline{LB}$ signals, valid data will be available on the lower eight, the upper eight or all sixteen output pins, t_{AVQV} after the last stable address.

If either of $\overline{E1}$, E2, $\overline{G}$ and $\overline{UB}$/$\overline{LB}$ is asserted after t_{AVQV} has elapsed, data access will be measured from the limiting parameter, t_{ELQV}, t_{GLQV} or t_{BLQV}, rather than the address.

Data out may be indeterminate at t_{ELQX}, t_{GLQX} and t_{BLQX}, but data lines will always be valid at t_{AVQV}.

See Figures 8, 9, 10 and Table 7 for details on Read mode AC timings and Characteristics.

Write Mode

The M68AW256D, when Chip Select (E2) is High, is in the Write Mode whenever the $\overline{W}$ and $\overline{E1}$ are Low. Either the Chip Enable Input ($\overline{E1}$) or the Write Enable input ($\overline{W}$) must be de-asserted during Address transitions for subsequent write cycles. When $\overline{E1}$ or $\overline{W}$ is Low, and $\overline{UB}$ or $\overline{LB}$ is Low, write cycle begins on the $\overline{W}$ or $\overline{E1}$ falling edge. When $\overline{E1}$ and $\overline{W}$ are Low, and $\overline{UB}$ = $\overline{LB}$ = High, write cycle begins on the first falling edge of $\overline{UB}$ or $\overline{LB}$. Therefore, address setup time is referenced to Write Enable, Chip Enables and $\overline{UB}$/$\overline{LB}$ as t_{AVWL}, t_{AVEL} and t_{AVBL} respectively, and is determined by the latter occurring falling edge.

The Write cycle can be terminated by the earlier rising edge of $\overline{E1}$, $\overline{W}$, $\overline{UB}$ and $\overline{LB}$.

If the Output is enabled ($\overline{E1}$ = Low, E2 = High, $\overline{G}$ = Low, $\overline{LB}$ or $\overline{UB}$ = Low), then $\overline{W}$ will return the outputs to high impedance within t_{WLQZ} of its falling edge. Care must be taken to avoid bus contention in this type of operation. Data input must be valid for t_{DVWH} before the rising edge of Write Enable, or for t_{DVEH} before the rising edge of $\overline{E1}$ or for t_{DVBH} before the rising edge of $\overline{UB}$/$\overline{LB}$, whichever occurs first, and remain valid for t_{WHDX}, t_{EHDX} and t_{BHDX} respectively.

See Figures 11, 12, 13 and Table 8 for details on Write mode AC timings and Characteristics.

Standby/Power-Down

The M68AW256D has a Chip Enable power down feature which invokes an automatic standby mode whenever Chip Enable is de-asserted ($\overline{E1}$ = High) or Chip Select is asserted (E2 = Low), or $\overline{UB}$/$\overline{LB}$ are de-asserted ($\overline{UB}$/$\overline{LB}$ = High). An Output Enable ($\overline{G}$) signal provides a high speed tri-state control, allowing fast read/write cycles to be achieved with the common I/O data bus. Operational modes are determined by device control inputs $\overline{W}$, $\overline{E1}$, $\overline{LB}$ and $\overline{UB}$ as summarized in the Operating Modes table (see Table 2).

Table 2. Operating Modes

Operation	$\overline{E1}$	E2	$\overline{W}$	$\overline{G}$	$\overline{LB}$	$\overline{UB}$	DQ0-DQ7	DQ8-DQ15	Power
Deselected (Standby/Power-Down)	V_{IH}	X	X	X	X	X	Hi-Z	Hi-Z	Standby (I_{SB})
	X	V_{IL}	X	X	X	X	Hi-Z	Hi-Z	Standby (I_{SB})
	X	X	X	X	V_{IH}	V_{IH}	Hi-Z	Hi-Z	Standby (I_{SB})
Lower Byte Read	V_{IL}	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IH}	Data Output	Hi-Z	Active (I_{CC})
Lower Byte Write	V_{IL}	V_{IH}	V_{IL}	X	V_{IL}	V_{IH}	Data Input	Hi-Z	Active (I_{CC})
Output Disabled	V_{IL}	V_{IH}	V_{IH}	V_{IH}	X	X	Hi-Z	Hi-Z	Active (I_{CC})
Upper Byte Read	V_{IL}	V_{IH}	V_{IH}	V_{IL}	V_{IH}	V_{IL}	Hi-Z	Data Output	Active (I_{CC})
Upper Byte Write	V_{IL}	V_{IH}	V_{IL}	X	V_{IH}	V_{IL}	Hi-Z	Data Input	Active (I_{CC})
Word Read	V_{IL}	V_{IH}	V_{IH}	V_{IL}	V_{IL}	V_{IL}	Data Output	Data Output	Active (I_{CC})
Word Write	V_{IL}	V_{IH}	V_{IL}	X	V_{IL}	V_{IL}	Data Input	Data Input	Active (I_{CC})
Output Disabled	V_{IL}	V_{IH}	X	V_{IH}	X	X	Hi-Z	Hi-Z	Active (I_{CC})

Note: 1. X = V_{IH} or V_{IL}.

MAXIMUM RATING

Stressing the device above the rating listed in the Absolute Maximum Ratings" table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

Table 3. Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
I_O (1)	Output Current	20	mA
T_A	Ambient Operating Temperature	–55 to 125	°C
T_{STG}	Storage Temperature	–65 to 150	°C
T_{LEAD}	Lead Temperature during Soldering(2)	260(3)	°C
V_{CC}	Supply Voltage	–0.5 to 4.6	V
V_{IO} (4)	Input or Output Voltage	–0.5 to V_{CC} +0.5	V
P_D	Power Dissipation	1	W

Note: 1. One output at a time, not to exceed 1 second duration.
2. Compliant with the ECOPACK® 7191395 specification for Lead-free soldering processes.
3. Not exceeding 250°C for more than 30s, and peaking at 260°C.
4. Up to a maximum operating V_{CC} of 3.6V only.

DC AND AC PARAMETERS

This section summarizes the operating and measurement conditions, as well as the DC and AC characteristics of the device. The parameters in the following DC and AC Characteristic tables are derived from tests performed under the Measurement Conditions listed in the relevant tables. Designers should check that the operating conditions in their projects match the measurement conditions when using the quoted parameters.

Table 4. Operating and AC Measurement Conditions

Parameter		M68AW256D
V_{CC} Supply Voltage		2.7 to 3.6V
Ambient Operating Temperature	Range 1	0 to 70°C
	Range 6	–40 to 85°C
Load Capacitance (C_L)		30pF
Output Circuit Protection Resistance (R_1)		3.0kΩ
Load Resistance (R_2)		3.1kΩ
Input Rise and Fall Times		1ns/V
Input Pulse Voltages		0 to V_{CC}
Input and Output Timing Ref. Voltages		$V_{CC}/2$
Output Transition Timing Ref. Voltages		$V_{RL} = 0.3V_{CC}$; $V_{RH} = 0.7V_{CC}$

Figure 6. AC Measurement I/O Waveform

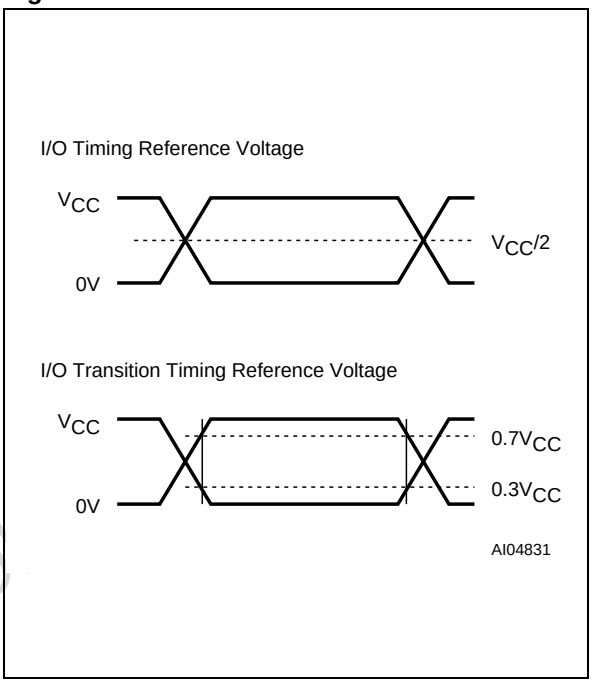


Figure 7. AC Measurement Load Circuit

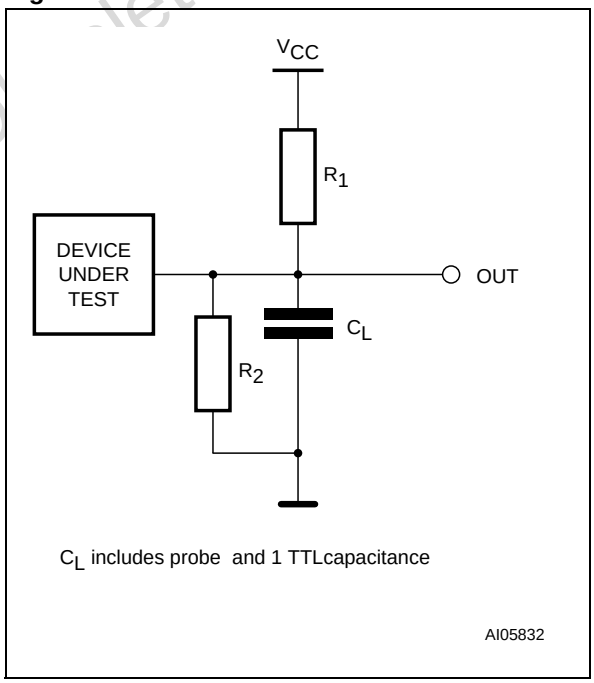


Table 5. Capacitance

Symbol	Parameter[1,2]	Test Condition	Min	Max	Unit
C_{IN}	Input Capacitance on all pins (except DQ)	V_{IN} = 0V		6	pF
C_{OUT}[3]	Output Capacitance	V_{OUT} = 0V		8	pF

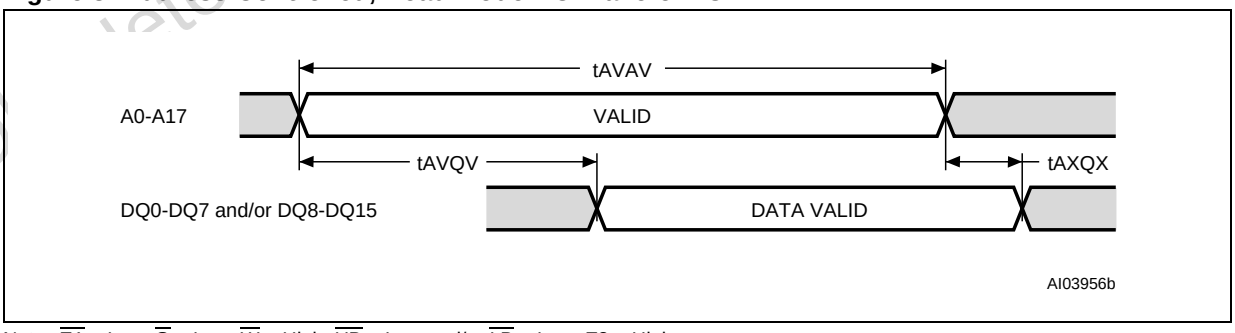
Note: 1. Sampled only, not 100% tested.
2. At T_A = 25°C, f = 1 MHz, V_{CC} = 3.0V.
3.Outputs deselected.

Table 6. DC Characteristics

Symbol	Parameter	Test Condition		M68AW256D				Unit
				-L		-N		
				Min	Max	Min	Max	
I_{CC1} (1)	Operating Supply Current	V_{CC} = 3.6V, f = 1/t_{AVAV}, I_{OUT} = 0mA	70ns		20		10	mA
			55ns		26		15	mA
I_{CC2}	Operating Supply Current	V_{CC} = 3.6V, f = 1MHz, I_{OUT} = 0mA			2		2	mA
I_{SB} (2)	Standby Supply Current CMOS	V_{CC} = 3.6V, f = 0, $\overline{E1} \geq V_{CC}$ –0.2V or E2 ≤ 0.2V or $\overline{LB}$=$\overline{UB}$ ≥V_{CC}–0.2V			20		20	µA
I_{LI}	Input Leakage Current	0V ≤ V_{IN} ≤ V_{CC}		–1	1	–1	1	µA
I_{LO} (3)	Output Leakage Current	0V ≤ V_{OUT} ≤ V_{CC}		–1	1	–1	1	µA
V_{IH}	Input High Voltage			2.2	V_{CC} + 0.5	2.2	V_{CC} + 0.5	V
V_{IL}	Input Low Voltage			–0.5	0.8	–0.5	0.8	V
V_{OH}	Output High Voltage	I_{OH} = –1.0mA		2.4		2.4		V
V_{OL}	Output Low Voltage	I_{OL} = 2.1mA			0.4		0.4	V

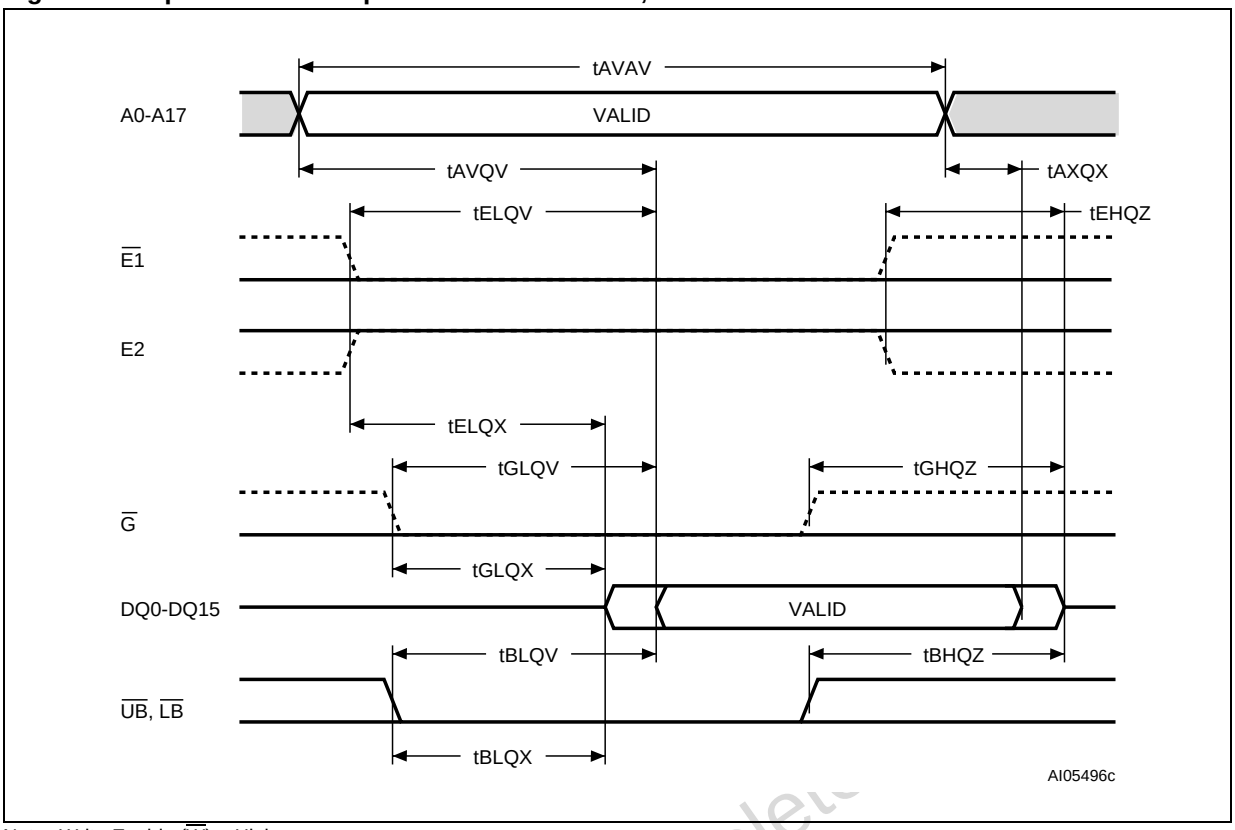
Note: 1. Average AC current, cycling at t_{AVAV} minimum.
2. All other Inputs at V_{IL} ≤0.2V or V_{IH} ≥V_{CC}–0.2V.
3.Output disabled.

Figure 8. Address Controlled, Read Mode AC Waveforms



Note: $\overline{E1}$ = Low, $\overline{G}$ = Low, $\overline{W}$ = High, $\overline{UB}$ = Low and/or $\overline{LB}$ = Low, E2 = High.

Figure 9. Chip Enable or Output Enable Controlled, Read Mode AC Waveforms.



Note: Write Enable ($\overline{W}$) = High.

Figure 10. Chip Enable or $\overline{UB}$/$\overline{LB}$ Controlled, Standby Mode AC Waveforms

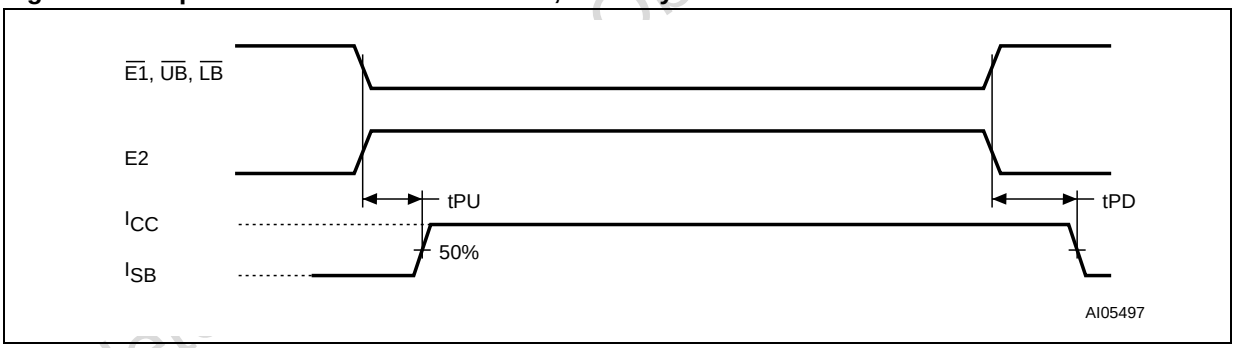


Table 7. Read and Standby Mode AC Characteristics

Symbol	Parameter		M68AW256D		Unit
			55	70	
t_{AVAV}	Read Cycle Time	Min	55	70	ns
t_{AVQV}	Address Valid to Output Valid	Max	55	70	ns
t_{AXQX} (1)	Data hold from address change	Min	5	5	ns
t_{BHQZ} (2,3)	Upper/Lower Byte Enable High to Output Hi-Z	Max	20	25	ns
t_{BLQV}	Upper/Lower Byte Enable Low to Output Valid	Max	55	70	ns
t_{BLQX} (1)	Upper/Lower Byte Enable Low to Output Transition	Min	5	5	ns
t_{EHQZ} (2,3)	Chip Enable High to Output Hi-Z	Max	20	25	ns
t_{ELQV}	Chip Enable Low to Output Valid	Max	55	70	ns
t_{ELQX} (1)	Chip Enable Low to Output Transition	Min	5	5	ns
t_{GHQZ} (2,3)	Output Enable High to Output Hi-Z	Max	20	25	ns
t_{GLQV}	Output Enable Low to Output Valid	Max	25	35	ns
t_{GLQX} (2)	Output Enable Low to Output Transition	Min	5	5	ns
t_{PD} (4)	Chip Enable or $\overline{UB}$/$\overline{LB}$ High to Power Down	Max	55	70	ns
t_{PU} (4)	Chip Enable or $\overline{UB}$/$\overline{LB}$ Low to Power Up	Min	0	0	ns

Note: 1. Test conditions assume transition timing reference level = $0.3V_{CC}$ or $0.7V_{CC}$.
2. At any given temperature and voltage condition, t_{GHQZ} is less than t_{GLQX}, t_{BHQZ} is less than t_{BLQX} and t_{EHQZ} is less than t_{ELQX} for any given device.
3. These parameters are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
4. Tested initially and after any design or process changes that may affect these parameters.

Figure 11. Write Enable Controlled, Write AC Waveforms

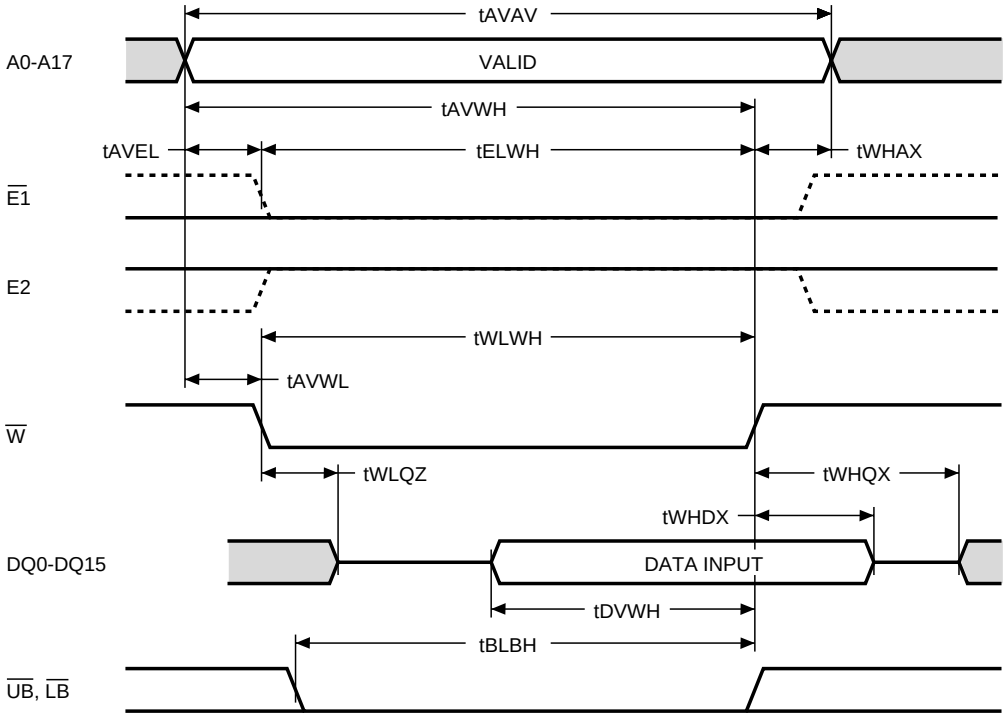


Figure 12. Chip Enable Controlled, Write AC Waveforms

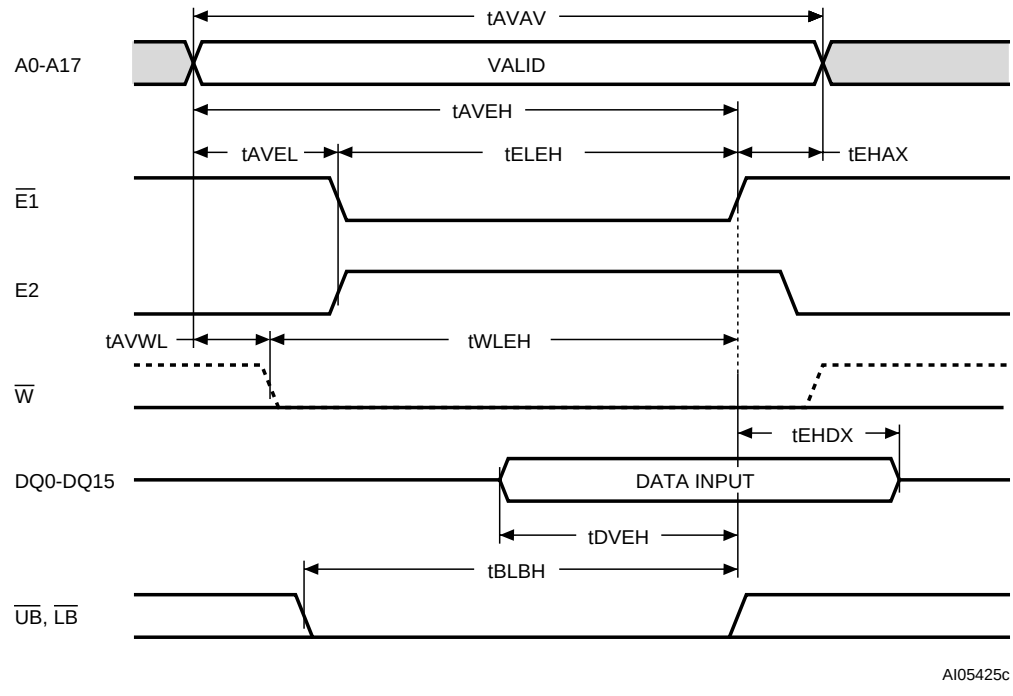
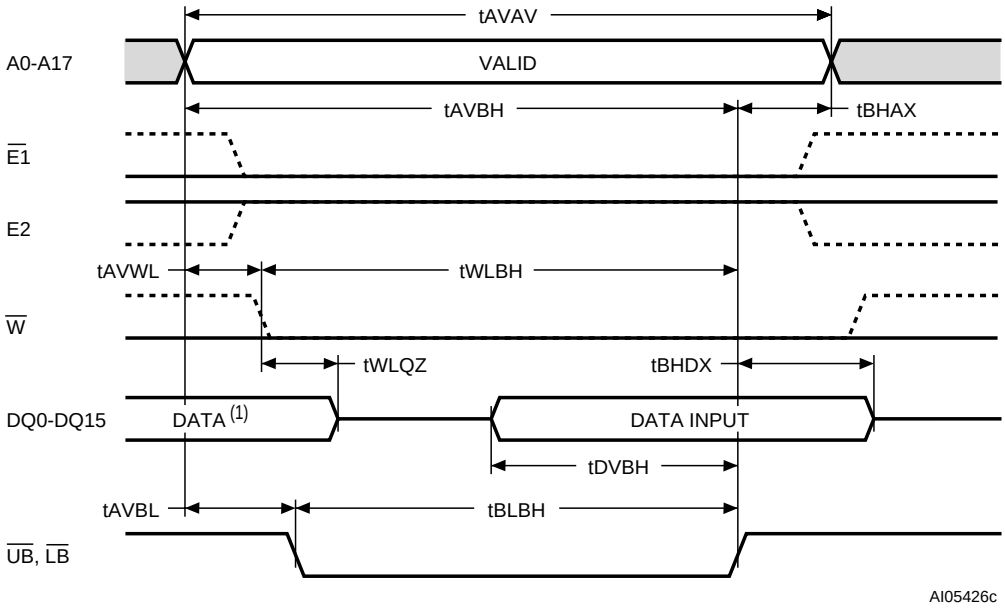


Figure 13. $\overline{UB}$/$\overline{LB}$ Controlled, Write AC Waveforms



Note: 1. During this period DQ0-DQ15 are in output state and input signals should not be applied.

Table 8. Write Mode AC Characteristics

Symbol	Parameter			M68AW256D		Unit
				55	70	
t_{AVAV}	Write Cycle Time		Min	55	70	ns
t_{AVBH}	Address Valid to $\overline{LB}$, $\overline{UB}$ High		Min	45	60	ns
t_{AVBL}	Addess Valid to $\overline{LB}$, $\overline{UB}$ Low		Min	0	0	ns
t_{AVEH}	Address Valid to Chip Enable High		Min	45	60	ns
t_{AVEL}	Address valid to Chip Enable Low		Min	0	0	ns
t_{AVWH}	Address Valid to Write Enable High		Min	45	60	ns
t_{AVWL}	Address Valid to Write Enable Low		Min	0	0	ns
t_{BHAX}	$\overline{LB}$, $\overline{UB}$ High to Address Transition		Min	0	0	ns
t_{BHDX}	$\overline{LB}$, $\overline{UB}$ High to Input Transition		Min	0	0	ns
t_{BLBH}	$\overline{LB}$, $\overline{UB}$ Low to $\overline{LB}$, $\overline{UB}$ High		Min	45	60	ns
t_{BLEH}	$\overline{LB}$, $\overline{UB}$ Low to Chip Enable High		Min	45	60	ns
t_{BLWH}	$\overline{LB}$, $\overline{UB}$ Low to Write Enable High		Min	45	60	ns
t_{DVBH}	Input Valid to $\overline{LB}$, $\overline{UB}$ High		Min	25	30	ns
t_{DVEH}	Input Valid to Chip Enable High		Min	25	30	ns
t_{DVWH}	Input Valid to Write Enable High		Min	25	30	ns
t_{EHAX}	Chip Enable High to Address Transition		Min	0	0	ns
t_{EHDX}	Chip enable High to Input Transition		Min	0	0	ns
t_{ELBH}	Chip Enable Low to $\overline{LB}$, $\overline{UB}$ High		Min	45	60	ns
t_{ELEH}	Chip Enable Low to Chip Enable High		Min	45	60	ns
t_{ELWH}	Chip Enable Low to Write Enable High		Min	45	60	ns
t_{WHAX}	Write Enable High to Address Transition		Min	0	0	ns
t_{WHDX}	Write Enable High to Input Transition		Min	0	0	ns
t_{WHQX} (1)	Write Enable High to Output Transition		Min	5	5	ns
t_{WLBH}	Write Enable Low to $\overline{LB}$, $\overline{UB}$ High		Min	45	60	ns
t_{WLEH}	Write Enable Low to Chip Enable High		Min	45	60	ns
t_{WLQZ} (1,2)	Write Enable Low to Output Hi-Z		Max	20	20	ns
t_{WLWH}	Write Enable Low to Write Enable High	-L version	Min	45	60	ns
		-N version	Min	40	50	ns

Note: 1. At any given temperature and voltage condition, t_{WLQZ} is less than t_{WHQX} for any given device.
2. These parameters are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.

Figure 14. $\overline{E1}$ Controlled, Low V_{CC} Data Retention AC Waveforms

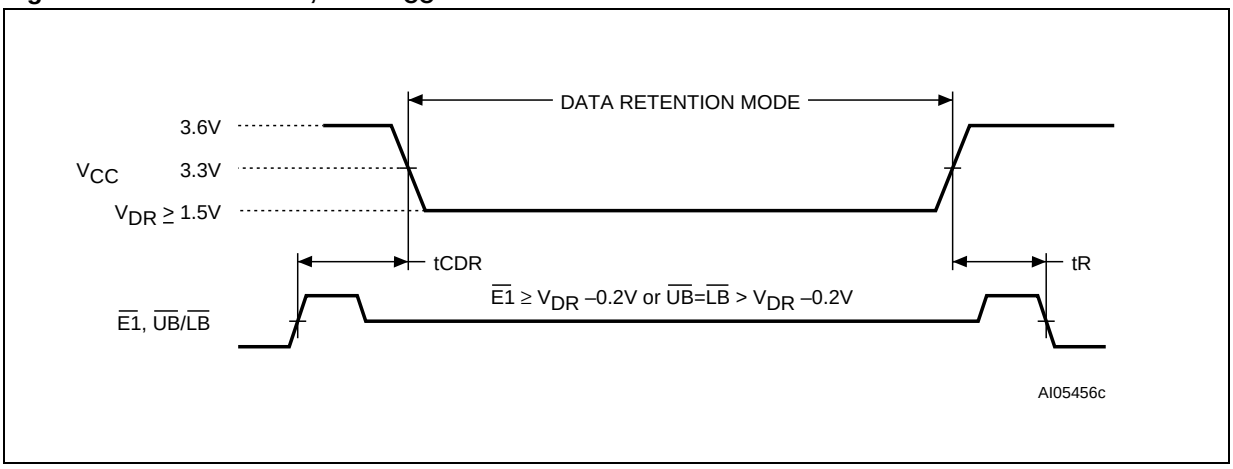


Figure 15. E2 Controlled, Low V_{CC} Data Retention AC Waveforms

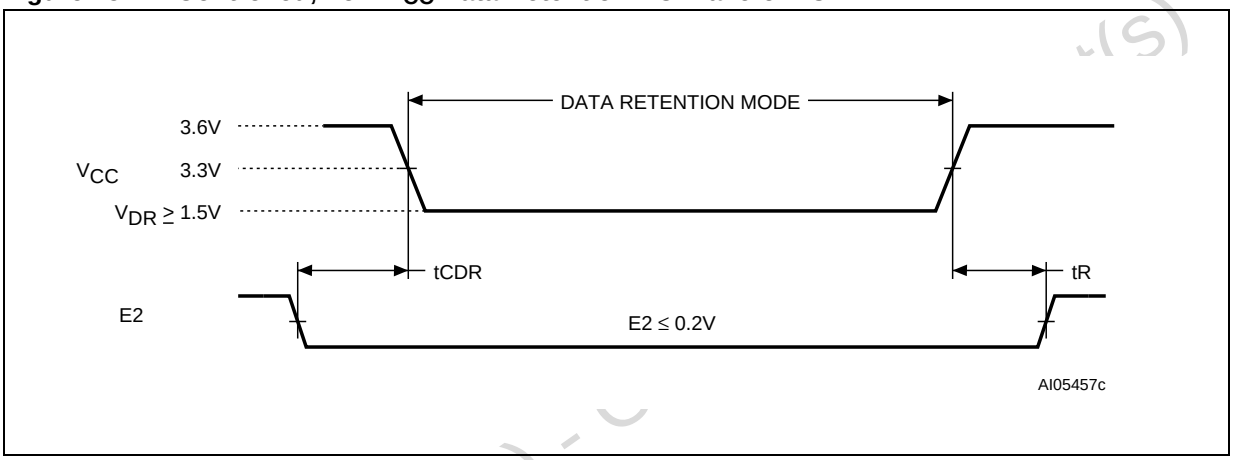


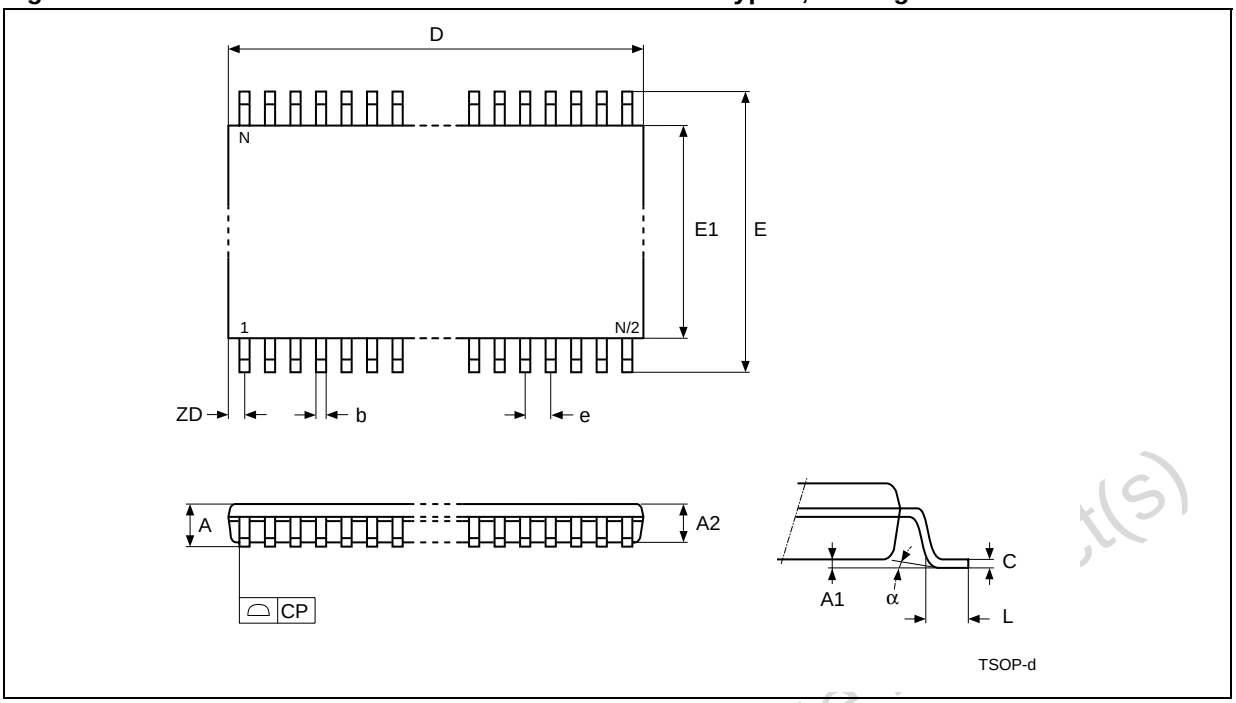
Table 9. Low V_{CC} Data Retention Characteristics

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
I_{CCDR} (1)	Supply Current (Data Retention)	V_{CC} = 1.5V, $\overline{E1} \geq V_{CC}$ –0.2V or E2 ≤ 0.2V or $\overline{UB}$ = $\overline{LB} \geq V_{CC}$ –0.2V, f = 0		10	20	µA
t_{CDR} (1,2)	Chip Deselected to Data Retention Time		0			ns
t_R (2)	Operation Recovery Time		t_{AVAV}			ns
V_{DR} (1)	Supply Voltage (Data Retention)	$\overline{E1} \geq V_{CC}$ –0.2V or E2 ≤ 0.2V or $\overline{UB}$ = $\overline{LB} \geq V_{CC}$ –0.2V, f = 0	1.5		3.6	V

Note: 1. All other Inputs at $V_{IH} \geq V_{CC}$ –0.2V or $V_{IL} \leq$ 0.2V.
2. Tested initially and after any design or process changes that may affect these parameters. t_{AVAV} is Read cycle time.
3. No input may exceed V_{CC} +0.2V.

PACKAGE MECHANICAL

Figure 16. TSOP44 II - 44 lead Plastic Thin Small Outline Type II, Package Outline

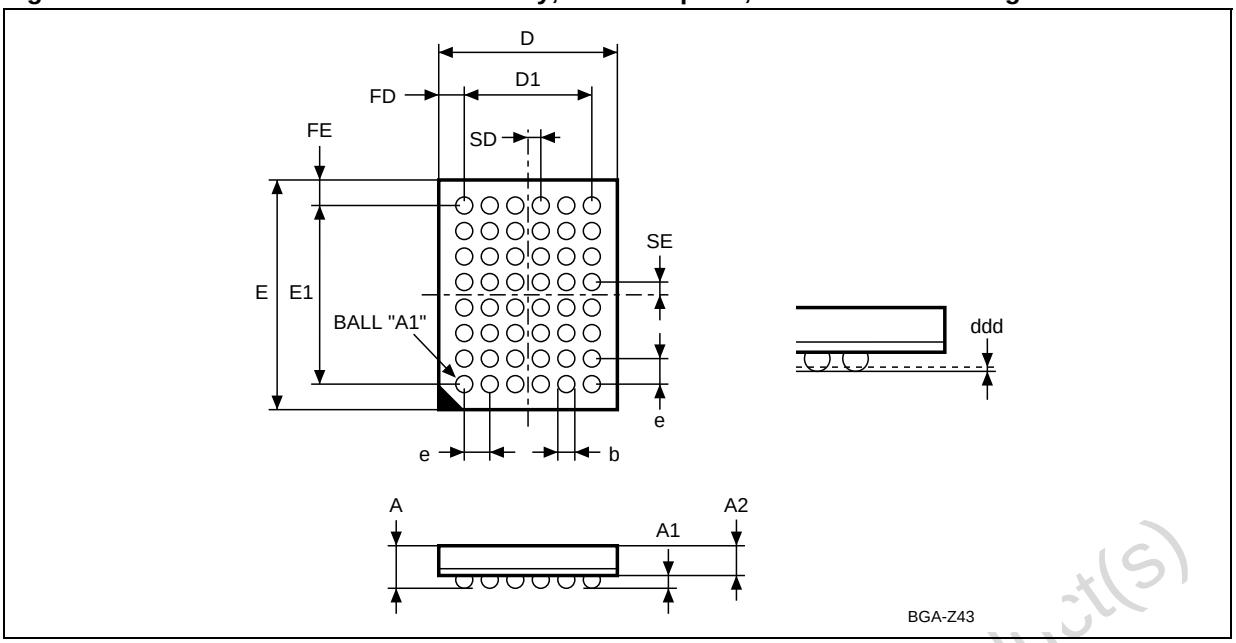


Note: Drawing is not to scale.

Table 10. TSOP 44 II - 44 lead Plastic Thin Small Outline Type II, Package Mechanical Data

Symbol	millimeters			inches		
	Typ	Min	Max	Typ	Min	Max
A			1.200			0.0472
A1		0.050	0.150		0.0020	0.0059
A2		0.950	1.050		0.0374	0.0413
b	0.350			0.0138		
c		0.120	0.210		0.0047	0.0083
D	18.410	–	–	0.7248	–	–
E	11.760	–	–	0.4630	–	–
E1	10.160	–	–	0.4000	–	–
e	0.800	–	–	0.0315	–	–
L	0.500	0.400	0.600	0.0197	0.0157	0.0236
ZD	0.805	–	–	0.0317	–	–
alfa		0	5		0	5
CP			0.100			0.0039
N	44			44		

Figure 17. TFBGA48 6x7mm - 6x8 ball array, 0.75 mm pitch, Bottom View Package Outline



Note: Drawing is not to scale.

Table 11. TFBGA48 6x7mm - 6x8 ball array, 0.75 mm pitch, Package Mechanical Data

Symbol	millimeters			inches		
	Typ	Min	Max	Typ	Min	Max
A			1.200			0.0472
A1		0.250	0.400		0.0098	0.0157
A2	0.790			0.0311		
b	0.400	0.350	0.450	0.0157	0.0138	0.0177
D	6.000	5.900	6.100	0.2362	0.2323	0.2402
D1	3.750			0.1476		
ddd			0.100			0.0039
E	7.000	6.900	7.100	0.2756	0.2717	0.2795
E1	5.250			0.2067		
e	0.750	–	–	0.0295	–	–
FD	1.125			0.0443		
FE	0.875			0.0344		
SD	0.375	–	–	0.0148	–	–
SE	0.375	–	–	0.0148	–	–

PART NUMBERING

Table 12. Ordering Information Scheme

Example: M68AW256 D L 55 ZB 6 T

Device Type
M68

Mode
A = Asynchronous

Operating Voltage
W = 2.7 to 3.6V

Array Organization
256 = 4 Mbit (256K x16)

Option 1
D = 2 Chip Enable; Write and Standby from $\overline{UB}$ and $\overline{LB}$

Option 2
N = N die
L = L die

Speed Class
55 = 55 ns
70 = 70 ns

Package
ND = TSOP 44 Type II
ZB = TFBGA48: 0.75 mm pitch

Operative Temperature
6 = –40 to 85 °C
1 = 0 to 70 °C

Shipping
T = Tape & Reel Packing

For a list of available options (Speed, Package, etc...) or for further information on any aspect of this device, please contact the STMicroelectronics Sales Office nearest to you.

REVISION HISTORY

Table 13. Document Revision History

Date	Version	Revision Details
February 2002	-01	First Issue
14-Mar-2002	-02	Tables 4, 6, 7 and 9 clarified Figures 3, 8, 9, 11, 12, 13 and 14 clarified
07-Jun-2002	-03	I_{CCDR} clarified (Table 9) I_{SB} clarified (Table 6)
24-Apr-2003	3.1	Revision numbering modified: a minor revision will be indicated by incrementing the digit after the dot, and a major revision, by incrementing the digit before the dot (revision version 03 equals 3.0). Modifications to values of I_{CC1} and I_{SB} for the 55 and 70ns devices Document promoted to full datasheet
25-Nov-2003	3.2	Option 2 updated in Part Numbering section. TLEAD parameter added in Table 3, Absolute Maximum Ratings. AC, DC Characteristics and waveforms grouped together.
20-Feb-2004	4.0	TFBGA48 7x8 replaced by TFBGA48 6x7: Figure 17.TFBGA48 6x7mm - 6x8 ball array, 0.75 mm pitch, Bottom View Package Outline and Table 11.TFBGA48 6x7mm - 6x8 ball array, 0.75 mm pitch, Package Mechanical Data updated. I_{CC1} and I_{SB} updated in Table 6.DC Characteristics. t_{WLWH} updated in Table 8. Write Mode AC Characteristics. V_{DR} minimum value changed in Figures 14 and 15 and Table 9.Low V_{CC} Data Retention Characteristics.